

# Global Electronic Underfill Encapsulants Supply, Demand and Key Producers, 2026-2032

<https://marketpublishers.com/r/G893B92C881FEN.html>

Date: August 2026

Pages: 166

Price: US\$ 4,480.00 (Single User License)

ID: G893B92C881FEN

## Abstracts

The global Electronic Underfill Encapsulants market size is expected to reach \$ 1285 million by 2032, rising at a market growth of 6.8% CAGR during the forecast period (2026-2032).

Electronic Underfill Encapsulants are liquid or film-type insulating protection materials used in semiconductor packaging and board-level electronic assembly. They are typically based on epoxy or modified epoxy resin systems and formulated with inorganic fillers, curing agents, coupling agents, toughening agents and rheology-control additives. The material is filled into the fine gap between a die, package, solder ball, bump and substrate through capillary flow, dispensing, pre-application, lamination or molding. After curing, it forms a continuous stress-buffering and sealing layer to improve solder-joint resistance to thermal cycling, drop impact, mechanical shock, moisture and long-term reliability stress.

Electronic Underfill Encapsulants are mainly used in flip-chip packages, chip-scale packages, ball grid array packages, wafer-level packages, system-in-package modules, 2.5D and 3D advanced packages, automotive electronics, AI server processors, memory devices, RF devices, sensors and power devices. Major production and R&D bases are concentrated in Japan, the United States, Germany, China, South Korea and Taiwan, China, where electronic chemicals, semiconductor packaging materials and advanced packaging supply chains are relatively mature.

In 2025, global Electronic Underfill Encapsulants production reached approximately 9,300-9,800 metric tons, with mainstream bulk FOB prices at approximately USD 80-86 per kg. Standard board-level capillary flow grades were generally priced below the market average, while semiconductor-grade, automotive-grade, high-thermal-

conductivity, low-warpage and advanced-packaging grades were priced significantly above average.

The global Electronic Underfill Encapsulants market is primarily driven by device miniaturization, higher interconnect density and rising packaging reliability requirements. As flip-chip, BGA, CSP, WLP, SiP, 2.5D and 3D advanced packaging technologies continue to penetrate high-value electronics, solder joints and bump structures are becoming smaller and more vulnerable to thermal expansion mismatch, mechanical shock, drop impact, vibration and moisture-related aging. Electronic Underfill Encapsulants form a stable protective layer within the narrow interconnect gap, redistribute solder-joint stress and extend interconnect lifetime. As a result, they have evolved from a reliability-enhancing material for consumer electronics into a critical packaging material for advanced semiconductors, automotive electronics, AI servers, memory devices and power electronics. Continued growth in AI processors, high-performance computing, vehicle electronic architectures and premium mobile devices will support demand for low-viscosity, fast-curing, low-ion, low-stress, thermally conductive and low-warpage formulations.

Key market challenges include long formulation qualification cycles, high customer certification barriers, raw-material consistency requirements and the fast evolution of advanced packaging processes. Underfill materials must simultaneously meet demanding targets for flow behavior, gap filling, interfacial adhesion, curing shrinkage, coefficient of thermal expansion, glass transition temperature, modulus, ionic impurities and moisture absorption. Improving one parameter often creates trade-offs with flowability, reliability or process window. Downstream customers apply strict requirements for failure rate, void control, warpage and batch consistency, making the entry barrier much higher than that of general electronic adhesives. Future competition will shift from product pricing alone to a broader contest in formulation capability, process compatibility, reliability data, joint development with customers and localized supply assurance. Suppliers with advanced packaging qualifications, automotive-grade certification and proven high-end electronic materials manufacturing experience will be better positioned to capture premium demand.

This report studies the global Electronic Underfill Encapsulants production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for Electronic Underfill Encapsulants and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends

and competition, as well as details the characteristics of Electronic Underfill Encapsulants that contribute to its increasing demand across many markets.

#### Highlights and key features of the study

Global Electronic Underfill Encapsulants total production and demand, 2021-2032, (Tons)

Global Electronic Underfill Encapsulants total production value, 2021-2032, (USD Million)

Global Electronic Underfill Encapsulants production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Tons), (based on production site)

Global Electronic Underfill Encapsulants consumption by region & country, CAGR, 2021-2032 & (Tons)

U.S. VS China: Electronic Underfill Encapsulants domestic production, consumption, key domestic manufacturers and share

Global Electronic Underfill Encapsulants production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Tons)

Global Electronic Underfill Encapsulants production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

Global Electronic Underfill Encapsulants production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Tons)

This report profiles key players in the global Electronic Underfill Encapsulants market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Henkel AG & Co. KGaA, NAMICS Corporation, Resonac Corporation, Panasonic Industry Co., Ltd., Shin-Etsu Chemical Co., Ltd., Sumitomo Bakelite Co., Ltd., Nagase ChemteX Corporation, Kyocera Corporation, ThreeBond Co., Ltd., H.B. Fuller Company, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World Electronic Underfill Encapsulants market

#### Detailed Segmentation:

Each section contains quantitative market data including market by value (US\$

Millions), volume (production, consumption) & (Tons) and average price (US\$/Ton) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

#### Global Electronic Underfill Encapsulants Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

#### Global Electronic Underfill Encapsulants Market, Segmentation by Type:

Capillary Flow Underfill

Molded Underfill

No Flow Underfill

Others

#### Global Electronic Underfill Encapsulants Market, Segmentation by Resin Chemistry:

Epoxy Based Materials

Modified Epoxy and Hybrid Materials

Others

#### Global Electronic Underfill Encapsulants Market, Segmentation by Package Type:

Flip Chip Packages

BGA and CSP Packages

WLP and Fan Out Packages

Others

#### Global Electronic Underfill Encapsulants Market, Segmentation by End Use Industry:

Consumer Electronics

Computing and Communications Infrastructure

Automotive Electronics

Others

#### Global Electronic Underfill Encapsulants Market, Segmentation by Application:

Package Level Underfill

Board Level Underfill

Others

#### Companies Profiled:

Henkel AG & Co. KGaA

NAMICS Corporation

Resonac Corporation

Panasonic Industry Co., Ltd.

Shin-Etsu Chemical Co., Ltd.

Sumitomo Bakelite Co., Ltd.

Nagase ChemteX Corporation

Kyocera Corporation

ThreeBond Co., Ltd.

H.B. Fuller Company

Parker Hannifin Corporation

AI Technology, Inc.

Zymet Inc.

Master Bond Inc.

Element Solutions Inc

AIM Solder

DELO Industrial Adhesives

Dr. H?nle AG

Protavic International

ROARTIS bvba

Darbond Technology Co., Ltd.

Weldtone Technology Co., Ltd.

Hubei Huitian New Materials Co., Ltd.

WaferChem Technology Corp.

Everwide Chemical Co.

#### Key Questions Answered:

1. How big is the global Electronic Underfill Encapsulants market?
2. What is the demand of the global Electronic Underfill Encapsulants market?
3. What is the year over year growth of the global Electronic Underfill Encapsulants market?
4. What is the production and production value of the global Electronic Underfill Encapsulants market?
5. Who are the key producers in the global Electronic Underfill Encapsulants market?
6. What are the growth factors driving the market demand?

## Contents

### 1 SUPPLY SUMMARY

- 1.1 Electronic Underfill Encapsulants Introduction
- 1.2 World Electronic Underfill Encapsulants Supply & Forecast
  - 1.2.1 World Electronic Underfill Encapsulants Production Value (2021 & 2025 & 2032)
  - 1.2.2 World Electronic Underfill Encapsulants Production (2021-2032)
  - 1.2.3 World Electronic Underfill Encapsulants Pricing Trends (2021-2032)
- 1.3 World Electronic Underfill Encapsulants Production by Region (Based on Production Site)
  - 1.3.1 World Electronic Underfill Encapsulants Production Value by Region (2021-2032)
  - 1.3.2 World Electronic Underfill Encapsulants Production by Region (2021-2032)
  - 1.3.3 World Electronic Underfill Encapsulants Average Price by Region (2021-2032)
  - 1.3.4 North America Electronic Underfill Encapsulants Production (2021-2032)
  - 1.3.5 Europe Electronic Underfill Encapsulants Production (2021-2032)
  - 1.3.6 China Electronic Underfill Encapsulants Production (2021-2032)
  - 1.3.7 Japan Electronic Underfill Encapsulants Production (2021-2032)
- 1.4 Market Drivers, Restraints and Trends
  - 1.4.1 Electronic Underfill Encapsulants Market Drivers
  - 1.4.2 Factors Affecting Demand
  - 1.4.3 Electronic Underfill Encapsulants Major Market Trends

### 2 DEMAND SUMMARY

- 2.1 World Electronic Underfill Encapsulants Demand (2021-2032)
- 2.2 World Electronic Underfill Encapsulants Consumption by Region
  - 2.2.1 World Electronic Underfill Encapsulants Consumption by Region (2021-2026)
  - 2.2.2 World Electronic Underfill Encapsulants Consumption Forecast by Region (2027-2032)
- 2.3 United States Electronic Underfill Encapsulants Consumption (2021-2032)
- 2.4 China Electronic Underfill Encapsulants Consumption (2021-2032)
- 2.5 Europe Electronic Underfill Encapsulants Consumption (2021-2032)
- 2.6 Japan Electronic Underfill Encapsulants Consumption (2021-2032)
- 2.7 South Korea Electronic Underfill Encapsulants Consumption (2021-2032)
- 2.8 ASEAN Electronic Underfill Encapsulants Consumption (2021-2032)
- 2.9 India Electronic Underfill Encapsulants Consumption (2021-2032)

### 3 WORLD MANUFACTURERS COMPETITIVE ANALYSIS

- 3.1 World Electronic Underfill Encapsulants Production Value by Manufacturer (2021-2026)
- 3.2 World Electronic Underfill Encapsulants Production by Manufacturer (2021-2026)
- 3.3 World Electronic Underfill Encapsulants Average Price by Manufacturer (2021-2026)
- 3.4 Electronic Underfill Encapsulants Company Evaluation Quadrant
- 3.5 Industry Rank and Concentration Rate (CR)
  - 3.5.1 Global Electronic Underfill Encapsulants Industry Rank of Major Manufacturers
  - 3.5.2 Global Concentration Ratios (CR4) for Electronic Underfill Encapsulants in 2025
  - 3.5.3 Global Concentration Ratios (CR8) for Electronic Underfill Encapsulants in 2025
- 3.6 Electronic Underfill Encapsulants Market: Overall Company Footprint Analysis
  - 3.6.1 Electronic Underfill Encapsulants Market: Region Footprint
  - 3.6.2 Electronic Underfill Encapsulants Market: Company Product Type Footprint
  - 3.6.3 Electronic Underfill Encapsulants Market: Company Product Application Footprint
- 3.7 Competitive Environment
  - 3.7.1 Historical Structure of the Industry
  - 3.7.2 Barriers of Market Entry
  - 3.7.3 Factors of Competition
- 3.8 New Entrant and Capacity Expansion Plans
- 3.9 Mergers, Acquisition, Agreements, and Collaborations

## **4 UNITED STATES VS CHINA VS REST OF THE WORLD**

- 4.1 United States VS China: Electronic Underfill Encapsulants Production Value Comparison
  - 4.1.1 United States VS China: Electronic Underfill Encapsulants Production Value Comparison (2021 & 2025 & 2032)
  - 4.1.2 United States VS China: Electronic Underfill Encapsulants Production Value Market Share Comparison (2021 & 2025 & 2032)
- 4.2 United States VS China: Electronic Underfill Encapsulants Production Comparison
  - 4.2.1 United States VS China: Electronic Underfill Encapsulants Production Comparison (2021 & 2025 & 2032)
  - 4.2.2 United States VS China: Electronic Underfill Encapsulants Production Market Share Comparison (2021 & 2025 & 2032)
- 4.3 United States VS China: Electronic Underfill Encapsulants Consumption Comparison
  - 4.3.1 United States VS China: Electronic Underfill Encapsulants Consumption Comparison (2021 & 2025 & 2032)
  - 4.3.2 United States VS China: Electronic Underfill Encapsulants Consumption Market

## Share Comparison (2021 & 2025 & 2032)

### 4.4 United States Based Electronic Underfill Encapsulants Manufacturers and Market Share, 2021-2026

#### 4.4.1 United States Based Electronic Underfill Encapsulants Manufacturers, Headquarters and Production Site (States, Country)

#### 4.4.2 United States Based Manufacturers Electronic Underfill Encapsulants Production Value (2021-2026)

#### 4.4.3 United States Based Manufacturers Electronic Underfill Encapsulants Production (2021-2026)

### 4.5 China Based Electronic Underfill Encapsulants Manufacturers and Market Share

#### 4.5.1 China Based Electronic Underfill Encapsulants Manufacturers, Headquarters and Production Site (Province, Country)

#### 4.5.2 China Based Manufacturers Electronic Underfill Encapsulants Production Value (2021-2026)

#### 4.5.3 China Based Manufacturers Electronic Underfill Encapsulants Production (2021-2026)

### 4.6 Rest of World Based Electronic Underfill Encapsulants Manufacturers and Market Share, 2021-2026

#### 4.6.1 Rest of World Based Electronic Underfill Encapsulants Manufacturers, Headquarters and Production Site (State, Country)

#### 4.6.2 Rest of World Based Manufacturers Electronic Underfill Encapsulants Production Value (2021-2026)

#### 4.6.3 Rest of World Based Manufacturers Electronic Underfill Encapsulants Production (2021-2026)

## 5 MARKET ANALYSIS BY TYPE

### 5.1 World Electronic Underfill Encapsulants Market Size Overview by Type: 2021 VS 2025 VS 2032

### 5.2 Segment Introduction by Type

#### 5.2.1 Capillary Flow Underfill

#### 5.2.2 Molded Underfill

#### 5.2.3 No Flow Underfill

#### 5.2.4 Others

### 5.3 Market Segment by Type

#### 5.3.1 World Electronic Underfill Encapsulants Production by Type (2021-2032)

#### 5.3.2 World Electronic Underfill Encapsulants Production Value by Type (2021-2032)

#### 5.3.3 World Electronic Underfill Encapsulants Average Price by Type (2021-2032)

## **6 MARKET ANALYSIS BY RESIN CHEMISTRY**

6.1 World Electronic Underfill Encapsulants Market Size Overview by Resin Chemistry:  
2021 VS 2025 VS 2032

6.2 Segment Introduction by Resin Chemistry

6.2.1 Epoxy Based Materials

6.2.2 Modified Epoxy and Hybrid Materials

6.2.3 Others

6.3 Market Segment by Resin Chemistry

6.3.1 World Electronic Underfill Encapsulants Production by Resin Chemistry  
(2021-2032)

6.3.2 World Electronic Underfill Encapsulants Production Value by Resin Chemistry  
(2021-2032)

6.3.3 World Electronic Underfill Encapsulants Average Price by Resin Chemistry  
(2021-2032)

## **7 MARKET ANALYSIS BY PACKAGE TYPE**

7.1 World Electronic Underfill Encapsulants Market Size Overview by Package Type:  
2021 VS 2025 VS 2032

7.2 Segment Introduction by Package Type

7.2.1 Flip Chip Packages

7.2.2 BGA and CSP Packages

7.2.3 WLP and Fan Out Packages

7.2.4 Others

7.3 Market Segment by Package Type

7.3.1 World Electronic Underfill Encapsulants Production by Package Type  
(2021-2032)

7.3.2 World Electronic Underfill Encapsulants Production Value by Package Type  
(2021-2032)

7.3.3 World Electronic Underfill Encapsulants Average Price by Package Type  
(2021-2032)

## **8 MARKET ANALYSIS BY END USE INDUSTRY**

8.1 World Electronic Underfill Encapsulants Market Size Overview by End Use Industry:  
2021 VS 2025 VS 2032

8.2 Segment Introduction by End Use Industry

8.2.1 Consumer Electronics

8.2.2 Computing and Communications Infrastructure

8.2.3 Automotive Electronics

8.2.4 Others

8.3 Market Segment by End Use Industry

8.3.1 World Electronic Underfill Encapsulants Production by End Use Industry  
(2021-2032)

8.3.2 World Electronic Underfill Encapsulants Production Value by End Use Industry  
(2021-2032)

8.3.3 World Electronic Underfill Encapsulants Average Price by End Use Industry  
(2021-2032)

## **9 MARKET ANALYSIS BY APPLICATION**

9.1 World Electronic Underfill Encapsulants Market Size Overview by Application: 2021  
VS 2025 VS 2032

9.2 Segment Introduction by Application

9.2.1 Package Level Underfill

9.2.2 Board Level Underfill

9.2.3 Others

9.3 Market Segment by Application

9.3.1 World Electronic Underfill Encapsulants Production by Application (2021-2032)  
9.3.2 World Electronic Underfill Encapsulants Production Value by Application  
(2021-2032)

9.3.3 World Electronic Underfill Encapsulants Average Price by Application  
(2021-2032)

## **10 COMPANY PROFILES**

10.1 Henkel AG & Co. KGaA

10.1.1 Henkel AG & Co. KGaA Details

10.1.2 Henkel AG & Co. KGaA Major Business

10.1.3 Henkel AG & Co. KGaA Electronic Underfill Encapsulants Product and Services

10.1.4 Henkel AG & Co. KGaA Electronic Underfill Encapsulants Production, Price,  
Value, Gross Margin and Market Share (2021-2026)

10.1.5 Henkel AG & Co. KGaA Recent Developments/Updates

10.1.6 Henkel AG & Co. KGaA Competitive Strengths & Weaknesses

10.2 NAMICS Corporation

10.2.1 NAMICS Corporation Details

10.2.2 NAMICS Corporation Major Business

- 10.2.3 NAMICS Corporation Electronic Underfill Encapsulants Product and Services
- 10.2.4 NAMICS Corporation Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 10.2.5 NAMICS Corporation Recent Developments/Updates
- 10.2.6 NAMICS Corporation Competitive Strengths & Weaknesses
- 10.3 Resonac Corporation
  - 10.3.1 Resonac Corporation Details
  - 10.3.2 Resonac Corporation Major Business
  - 10.3.3 Resonac Corporation Electronic Underfill Encapsulants Product and Services
  - 10.3.4 Resonac Corporation Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.3.5 Resonac Corporation Recent Developments/Updates
  - 10.3.6 Resonac Corporation Competitive Strengths & Weaknesses
- 10.4 Panasonic Industry Co., Ltd.
  - 10.4.1 Panasonic Industry Co., Ltd. Details
  - 10.4.2 Panasonic Industry Co., Ltd. Major Business
  - 10.4.3 Panasonic Industry Co., Ltd. Electronic Underfill Encapsulants Product and Services
  - 10.4.4 Panasonic Industry Co., Ltd. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.4.5 Panasonic Industry Co., Ltd. Recent Developments/Updates
  - 10.4.6 Panasonic Industry Co., Ltd. Competitive Strengths & Weaknesses
- 10.5 Shin-Etsu Chemical Co., Ltd.
  - 10.5.1 Shin-Etsu Chemical Co., Ltd. Details
  - 10.5.2 Shin-Etsu Chemical Co., Ltd. Major Business
  - 10.5.3 Shin-Etsu Chemical Co., Ltd. Electronic Underfill Encapsulants Product and Services
  - 10.5.4 Shin-Etsu Chemical Co., Ltd. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.5.5 Shin-Etsu Chemical Co., Ltd. Recent Developments/Updates
  - 10.5.6 Shin-Etsu Chemical Co., Ltd. Competitive Strengths & Weaknesses
- 10.6 Sumitomo Bakelite Co., Ltd.
  - 10.6.1 Sumitomo Bakelite Co., Ltd. Details
  - 10.6.2 Sumitomo Bakelite Co., Ltd. Major Business
  - 10.6.3 Sumitomo Bakelite Co., Ltd. Electronic Underfill Encapsulants Product and Services
  - 10.6.4 Sumitomo Bakelite Co., Ltd. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.6.5 Sumitomo Bakelite Co., Ltd. Recent Developments/Updates

- 10.6.6 Sumitomo Bakelite Co., Ltd. Competitive Strengths & Weaknesses
- 10.7 Nagase ChemteX Corporation
  - 10.7.1 Nagase ChemteX Corporation Details
  - 10.7.2 Nagase ChemteX Corporation Major Business
  - 10.7.3 Nagase ChemteX Corporation Electronic Underfill Encapsulants Product and Services
  - 10.7.4 Nagase ChemteX Corporation Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.7.5 Nagase ChemteX Corporation Recent Developments/Updates
  - 10.7.6 Nagase ChemteX Corporation Competitive Strengths & Weaknesses
- 10.8 Kyocera Corporation
  - 10.8.1 Kyocera Corporation Details
  - 10.8.2 Kyocera Corporation Major Business
  - 10.8.3 Kyocera Corporation Electronic Underfill Encapsulants Product and Services
  - 10.8.4 Kyocera Corporation Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.8.5 Kyocera Corporation Recent Developments/Updates
  - 10.8.6 Kyocera Corporation Competitive Strengths & Weaknesses
- 10.9 ThreeBond Co., Ltd.
  - 10.9.1 ThreeBond Co., Ltd. Details
  - 10.9.2 ThreeBond Co., Ltd. Major Business
  - 10.9.3 ThreeBond Co., Ltd. Electronic Underfill Encapsulants Product and Services
  - 10.9.4 ThreeBond Co., Ltd. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.9.5 ThreeBond Co., Ltd. Recent Developments/Updates
  - 10.9.6 ThreeBond Co., Ltd. Competitive Strengths & Weaknesses
- 10.10 H.B. Fuller Company
  - 10.10.1 H.B. Fuller Company Details
  - 10.10.2 H.B. Fuller Company Major Business
  - 10.10.3 H.B. Fuller Company Electronic Underfill Encapsulants Product and Services
  - 10.10.4 H.B. Fuller Company Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.10.5 H.B. Fuller Company Recent Developments/Updates
  - 10.10.6 H.B. Fuller Company Competitive Strengths & Weaknesses
- 10.11 Parker Hannifin Corporation
  - 10.11.1 Parker Hannifin Corporation Details
  - 10.11.2 Parker Hannifin Corporation Major Business
  - 10.11.3 Parker Hannifin Corporation Electronic Underfill Encapsulants Product and Services

10.11.4 Parker Hannifin Corporation Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)

10.11.5 Parker Hannifin Corporation Recent Developments/Updates

10.11.6 Parker Hannifin Corporation Competitive Strengths & Weaknesses

10.12 AI Technology, Inc.

10.12.1 AI Technology, Inc. Details

10.12.2 AI Technology, Inc. Major Business

10.12.3 AI Technology, Inc. Electronic Underfill Encapsulants Product and Services

10.12.4 AI Technology, Inc. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)

10.12.5 AI Technology, Inc. Recent Developments/Updates

10.12.6 AI Technology, Inc. Competitive Strengths & Weaknesses

10.13 Zymet Inc.

10.13.1 Zymet Inc. Details

10.13.2 Zymet Inc. Major Business

10.13.3 Zymet Inc. Electronic Underfill Encapsulants Product and Services

10.13.4 Zymet Inc. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)

10.13.5 Zymet Inc. Recent Developments/Updates

10.13.6 Zymet Inc. Competitive Strengths & Weaknesses

10.14 Master Bond Inc.

10.14.1 Master Bond Inc. Details

10.14.2 Master Bond Inc. Major Business

10.14.3 Master Bond Inc. Electronic Underfill Encapsulants Product and Services

10.14.4 Master Bond Inc. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)

10.14.5 Master Bond Inc. Recent Developments/Updates

10.14.6 Master Bond Inc. Competitive Strengths & Weaknesses

10.15 Element Solutions Inc

10.15.1 Element Solutions Inc Details

10.15.2 Element Solutions Inc Major Business

10.15.3 Element Solutions Inc Electronic Underfill Encapsulants Product and Services

10.15.4 Element Solutions Inc Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)

10.15.5 Element Solutions Inc Recent Developments/Updates

10.15.6 Element Solutions Inc Competitive Strengths & Weaknesses

10.16 AIM Solder

10.16.1 AIM Solder Details

10.16.2 AIM Solder Major Business

- 10.16.3 AIM Solder Electronic Underfill Encapsulants Product and Services
- 10.16.4 AIM Solder Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 10.16.5 AIM Solder Recent Developments/Updates
- 10.16.6 AIM Solder Competitive Strengths & Weaknesses
- 10.17 DELO Industrial Adhesives
  - 10.17.1 DELO Industrial Adhesives Details
  - 10.17.2 DELO Industrial Adhesives Major Business
  - 10.17.3 DELO Industrial Adhesives Electronic Underfill Encapsulants Product and Services
  - 10.17.4 DELO Industrial Adhesives Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.17.5 DELO Industrial Adhesives Recent Developments/Updates
  - 10.17.6 DELO Industrial Adhesives Competitive Strengths & Weaknesses
- 10.18 Dr. H?nle AG
  - 10.18.1 Dr. H?nle AG Details
  - 10.18.2 Dr. H?nle AG Major Business
  - 10.18.3 Dr. H?nle AG Electronic Underfill Encapsulants Product and Services
  - 10.18.4 Dr. H?nle AG Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.18.5 Dr. H?nle AG Recent Developments/Updates
  - 10.18.6 Dr. H?nle AG Competitive Strengths & Weaknesses
- 10.19 Protavic International
  - 10.19.1 Protavic International Details
  - 10.19.2 Protavic International Major Business
  - 10.19.3 Protavic International Electronic Underfill Encapsulants Product and Services
  - 10.19.4 Protavic International Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.19.5 Protavic International Recent Developments/Updates
  - 10.19.6 Protavic International Competitive Strengths & Weaknesses
- 10.20 ROARTIS bvba
  - 10.20.1 ROARTIS bvba Details
  - 10.20.2 ROARTIS bvba Major Business
  - 10.20.3 ROARTIS bvba Electronic Underfill Encapsulants Product and Services
  - 10.20.4 ROARTIS bvba Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
  - 10.20.5 ROARTIS bvba Recent Developments/Updates
  - 10.20.6 ROARTIS bvba Competitive Strengths & Weaknesses
- 10.21 Darbond Technology Co., Ltd.

- 10.21.1 Darbond Technology Co., Ltd. Details
- 10.21.2 Darbond Technology Co., Ltd. Major Business
- 10.21.3 Darbond Technology Co., Ltd. Electronic Underfill Encapsulants Product and Services
- 10.21.4 Darbond Technology Co., Ltd. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 10.21.5 Darbond Technology Co., Ltd. Recent Developments/Updates
- 10.21.6 Darbond Technology Co., Ltd. Competitive Strengths & Weaknesses
- 10.22 Weldtone Technology Co., Ltd.
- 10.22.1 Weldtone Technology Co., Ltd. Details
- 10.22.2 Weldtone Technology Co., Ltd. Major Business
- 10.22.3 Weldtone Technology Co., Ltd. Electronic Underfill Encapsulants Product and Services
- 10.22.4 Weldtone Technology Co., Ltd. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 10.22.5 Weldtone Technology Co., Ltd. Recent Developments/Updates
- 10.22.6 Weldtone Technology Co., Ltd. Competitive Strengths & Weaknesses
- 10.23 Hubei Huitian New Materials Co., Ltd.
- 10.23.1 Hubei Huitian New Materials Co., Ltd. Details
- 10.23.2 Hubei Huitian New Materials Co., Ltd. Major Business
- 10.23.3 Hubei Huitian New Materials Co., Ltd. Electronic Underfill Encapsulants Product and Services
- 10.23.4 Hubei Huitian New Materials Co., Ltd. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 10.23.5 Hubei Huitian New Materials Co., Ltd. Recent Developments/Updates
- 10.23.6 Hubei Huitian New Materials Co., Ltd. Competitive Strengths & Weaknesses
- 10.24 WaferChem Technology Corp.
- 10.24.1 WaferChem Technology Corp. Details
- 10.24.2 WaferChem Technology Corp. Major Business
- 10.24.3 WaferChem Technology Corp. Electronic Underfill Encapsulants Product and Services
- 10.24.4 WaferChem Technology Corp. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)
- 10.24.5 WaferChem Technology Corp. Recent Developments/Updates
- 10.24.6 WaferChem Technology Corp. Competitive Strengths & Weaknesses
- 10.25 Everwide Chemical Co.
- 10.25.1 Everwide Chemical Co. Details
- 10.25.2 Everwide Chemical Co. Major Business
- 10.25.3 Everwide Chemical Co. Electronic Underfill Encapsulants Product and

## Services

10.25.4 Everwide Chemical Co. Electronic Underfill Encapsulants Production, Price, Value, Gross Margin and Market Share (2021-2026)

10.25.5 Everwide Chemical Co. Recent Developments/Updates

10.25.6 Everwide Chemical Co. Competitive Strengths & Weaknesses

## **11 INDUSTRY CHAIN ANALYSIS**

11.1 Electronic Underfill Encapsulants Industry Chain

11.2 Electronic Underfill Encapsulants Upstream Analysis

11.2.1 Electronic Underfill Encapsulants Core Raw Materials

11.2.2 Main Manufacturers of Electronic Underfill Encapsulants Core Raw Materials

11.3 Midstream Analysis

11.4 Downstream Analysis

11.5 Electronic Underfill Encapsulants Production Mode

11.6 Electronic Underfill Encapsulants Procurement Model

11.7 Electronic Underfill Encapsulants Industry Sales Model and Sales Channels

11.7.1 Electronic Underfill Encapsulants Sales Model

11.7.2 Electronic Underfill Encapsulants Typical Distributors

## **12 RESEARCH FINDINGS AND CONCLUSION**

## **13 APPENDIX**

13.1 Methodology

13.2 Research Process and Data Source

13.3 Disclaimer

## List Of Tables

### LIST OF TABLES

Table 1. World Electronic Underfill Encapsulants Production Value by Region (2021, 2025 and 2032) & (USD Million)

Table 2. World Electronic Underfill Encapsulants Production Value by Region (2021-2026) & (USD Million)

Table 3. World Electronic Underfill Encapsulants Production Value by Region (2027-2032) & (USD Million)

Table 4. World Electronic Underfill Encapsulants Production Value Market Share by Region (2021-2026)

Table 5. World Electronic Underfill Encapsulants Production Value Market Share by Region (2027-2032)

Table 6. World Electronic Underfill Encapsulants Production by Region (2021-2026) & (Tons)

Table 7. World Electronic Underfill Encapsulants Production by Region (2027-2032) & (Tons)

Table 8. World Electronic Underfill Encapsulants Production Market Share by Region (2021-2026)

Table 9. World Electronic Underfill Encapsulants Production Market Share by Region (2027-2032)

Table 10. World Electronic Underfill Encapsulants Average Price by Region (2021-2026) & (US\$/Ton)

Table 11. World Electronic Underfill Encapsulants Average Price by Region (2027-2032) & (US\$/Ton)

Table 12. Electronic Underfill Encapsulants Major Market Trends

Table 13. World Electronic Underfill Encapsulants Consumption Growth Rate Forecast by Region (2021 & 2025 & 2032) & (Tons)

Table 14. World Electronic Underfill Encapsulants Consumption by Region (2021-2026) & (Tons)

Table 15. World Electronic Underfill Encapsulants Consumption Forecast by Region (2027-2032) & (Tons)

Table 16. World Electronic Underfill Encapsulants Production Value by Manufacturer (2021-2026) & (USD Million)

Table 17. Production Value Market Share of Key Electronic Underfill Encapsulants Producers in 2025

Table 18. World Electronic Underfill Encapsulants Production by Manufacturer (2021-2026) & (Tons)

Table 19. Production Market Share of Key Electronic Underfill Encapsulants Producers in 2025

Table 20. World Electronic Underfill Encapsulants Average Price by Manufacturer (2021-2026) & (US\$/Ton)

Table 21. Global Electronic Underfill Encapsulants Company Evaluation Quadrant

Table 22. World Electronic Underfill Encapsulants Industry Rank of Major Manufacturers, Based on Production Value in 2025

Table 23. Head Office and Electronic Underfill Encapsulants Production Site of Key Manufacturer

Table 24. Electronic Underfill Encapsulants Market: Company Product Type Footprint

Table 25. Electronic Underfill Encapsulants Market: Company Product Application Footprint

Table 26. Electronic Underfill Encapsulants Competitive Factors

Table 27. Electronic Underfill Encapsulants New Entrant and Capacity Expansion Plans

Table 28. Electronic Underfill Encapsulants Mergers & Acquisitions Activity

Table 29. United States VS China Electronic Underfill Encapsulants Production Value Comparison, (2021 & 2025 & 2032) & (USD Million)

Table 30. United States VS China Electronic Underfill Encapsulants Production Comparison, (2021 & 2025 & 2032) & (Tons)

Table 31. United States VS China Electronic Underfill Encapsulants Consumption Comparison, (2021 & 2025 & 2032) & (Tons)

Table 32. United States Based Electronic Underfill Encapsulants Manufacturers, Headquarters and Production Site (States, Country)

Table 33. United States Based Manufacturers Electronic Underfill Encapsulants Production Value, (2021-2026) & (USD Million)

Table 34. United States Based Manufacturers Electronic Underfill Encapsulants Production Value Market Share (2021-2026)

Table 35. United States Based Manufacturers Electronic Underfill Encapsulants Production (2021-2026) & (Tons)

Table 36. United States Based Manufacturers Electronic Underfill Encapsulants Production Market Share (2021-2026)

Table 37. China Based Electronic Underfill Encapsulants Manufacturers, Headquarters and Production Site (Province, Country)

Table 38. China Based Manufacturers Electronic Underfill Encapsulants Production Value, (2021-2026) & (USD Million)

Table 39. China Based Manufacturers Electronic Underfill Encapsulants Production Value Market Share (2021-2026)

Table 40. China Based Manufacturers Electronic Underfill Encapsulants Production, (2021-2026) & (Tons)

Table 41. China Based Manufacturers Electronic Underfill Encapsulants Production Market Share (2021-2026)

Table 42. Rest of World Based Electronic Underfill Encapsulants Manufacturers, Headquarters and Production Site (State, Country)

Table 43. Rest of World Based Manufacturers Electronic Underfill Encapsulants Production Value, (2021-2026) & (USD Million)

Table 44. Rest of World Based Manufacturers Electronic Underfill Encapsulants Production Value Market Share (2021-2026)

Table 45. Rest of World Based Manufacturers Electronic Underfill Encapsulants Production, (2021-2026) & (Tons)

Table 46. Rest of World Based Manufacturers Electronic Underfill Encapsulants Production Market Share (2021-2026)

Table 47. World Electronic Underfill Encapsulants Production Value by Type, (USD Million), 2021 & 2025 & 2032

Table 48. World Electronic Underfill Encapsulants Production by Type (2021-2026) & (Tons)

Table 49. World Electronic Underfill Encapsulants Production by Type (2027-2032) & (Tons)

Table 50. World Electronic Underfill Encapsulants Production Value by Type (2021-2026) & (USD Million)

Table 51. World Electronic Underfill Encapsulants Production Value by Type (2027-2032) & (USD Million)

Table 52. World Electronic Underfill Encapsulants Average Price by Type (2021-2026) & (US\$/Ton)

Table 53. World Electronic Underfill Encapsulants Average Price by Type (2027-2032) & (US\$/Ton)

Table 54. World Electronic Underfill Encapsulants Production Value by Resin Chemistry, (USD Million), 2021 & 2025 & 2032

Table 55. World Electronic Underfill Encapsulants Production by Resin Chemistry (2021-2026) & (Tons)

Table 56. World Electronic Underfill Encapsulants Production by Resin Chemistry (2027-2032) & (Tons)

Table 57. World Electronic Underfill Encapsulants Production Value by Resin Chemistry (2021-2026) & (USD Million)

Table 58. World Electronic Underfill Encapsulants Production Value by Resin Chemistry (2027-2032) & (USD Million)

Table 59. World Electronic Underfill Encapsulants Average Price by Resin Chemistry (2021-2026) & (US\$/Ton)

Table 60. World Electronic Underfill Encapsulants Average Price by Resin Chemistry

(2027-2032) & (US\$/Ton)

Table 61. World Electronic Underfill Encapsulants Production Value by Package Type, (USD Million), 2021 & 2025 & 2032

Table 62. World Electronic Underfill Encapsulants Production by Package Type (2021-2026) & (Tons)

Table 63. World Electronic Underfill Encapsulants Production by Package Type (2027-2032) & (Tons)

Table 64. World Electronic Underfill Encapsulants Production Value by Package Type (2021-2026) & (USD Million)

Table 65. World Electronic Underfill Encapsulants Production Value by Package Type (2027-2032) & (USD Million)

Table 66. World Electronic Underfill Encapsulants Average Price by Package Type (2021-2026) & (US\$/Ton)

Table 67. World Electronic Underfill Encapsulants Average Price by Package Type (2027-2032) & (US\$/Ton)

Table 68. World Electronic Underfill Encapsulants Production Value by End Use Industry, (USD Million), 2021 & 2025 & 2032

Table 69. World Electronic Underfill Encapsulants Production by End Use Industry (2021-2026) & (Tons)

Table 70. World Electronic Underfill Encapsulants Production by End Use Industry (2027-2032) & (Tons)

Table 71. World Electronic Underfill Encapsulants Production Value by End Use Industry (2021-2026) & (USD Million)

Table 72. World Electronic Underfill Encapsulants Production Value by End Use Industry (2027-2032) & (USD Million)

Table 73. World Electronic Underfill Encapsulants Average Price by End Use Industry (2021-2026) & (US\$/Ton)

Table 74. World Electronic Underfill Encapsulants Average Price by End Use Industry (2027-2032) & (US\$/Ton)

Table 75. World Electronic Underfill Encapsulants Production Value by Application, (USD Million), 2021 & 2025 & 2032

Table 76. World Electronic Underfill Encapsulants Production by Application (2021-2026) & (Tons)

Table 77. World Electronic Underfill Encapsulants Production by Application (2027-2032) & (Tons)

Table 78. World Electronic Underfill Encapsulants Production Value by Application (2021-2026) & (USD Million)

Table 79. World Electronic Underfill Encapsulants Production Value by Application (2027-2032) & (USD Million)

Table 80. World Electronic Underfill Encapsulants Average Price by Application (2021-2026) & (US\$/Ton)

Table 81. World Electronic Underfill Encapsulants Average Price by Application (2027-2032) & (US\$/Ton)

Table 82. Henkel AG & Co. KGaA Basic Information, Manufacturing Base and Competitors

Table 83. Henkel AG & Co. KGaA Major Business

Table 84. Henkel AG & Co. KGaA Electronic Underfill Encapsulants Product and Services

Table 85. Henkel AG & Co. KGaA Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 86. Henkel AG & Co. KGaA Recent Developments/Updates

Table 87. Henkel AG & Co. KGaA Competitive Strengths & Weaknesses

Table 88. NAMICS Corporation Basic Information, Manufacturing Base and Competitors

Table 89. NAMICS Corporation Major Business

Table 90. NAMICS Corporation Electronic Underfill Encapsulants Product and Services

Table 91. NAMICS Corporation Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 92. NAMICS Corporation Recent Developments/Updates

Table 93. NAMICS Corporation Competitive Strengths & Weaknesses

Table 94. Resonac Corporation Basic Information, Manufacturing Base and Competitors

Table 95. Resonac Corporation Major Business

Table 96. Resonac Corporation Electronic Underfill Encapsulants Product and Services

Table 97. Resonac Corporation Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 98. Resonac Corporation Recent Developments/Updates

Table 99. Resonac Corporation Competitive Strengths & Weaknesses

Table 100. Panasonic Industry Co., Ltd. Basic Information, Manufacturing Base and Competitors

Table 101. Panasonic Industry Co., Ltd. Major Business

Table 102. Panasonic Industry Co., Ltd. Electronic Underfill Encapsulants Product and Services

Table 103. Panasonic Industry Co., Ltd. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 104. Panasonic Industry Co., Ltd. Recent Developments/Updates

|                                                                                                                                                                                          |
|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Table 105. Panasonic Industry Co., Ltd. Competitive Strengths & Weaknesses                                                                                                               |
| Table 106. Shin-Etsu Chemical Co., Ltd. Basic Information, Manufacturing Base and Competitors                                                                                            |
| Table 107. Shin-Etsu Chemical Co., Ltd. Major Business                                                                                                                                   |
| Table 108. Shin-Etsu Chemical Co., Ltd. Electronic Underfill Encapsulants Product and Services                                                                                           |
| Table 109. Shin-Etsu Chemical Co., Ltd. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026) |
| Table 110. Shin-Etsu Chemical Co., Ltd. Recent Developments/Updates                                                                                                                      |
| Table 111. Shin-Etsu Chemical Co., Ltd. Competitive Strengths & Weaknesses                                                                                                               |
| Table 112. Sumitomo Bakelite Co., Ltd. Basic Information, Manufacturing Base and Competitors                                                                                             |
| Table 113. Sumitomo Bakelite Co., Ltd. Major Business                                                                                                                                    |
| Table 114. Sumitomo Bakelite Co., Ltd. Electronic Underfill Encapsulants Product and Services                                                                                            |
| Table 115. Sumitomo Bakelite Co., Ltd. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)  |
| Table 116. Sumitomo Bakelite Co., Ltd. Recent Developments/Updates                                                                                                                       |
| Table 117. Sumitomo Bakelite Co., Ltd. Competitive Strengths & Weaknesses                                                                                                                |
| Table 118. Nagase ChemteX Corporation Basic Information, Manufacturing Base and Competitors                                                                                              |
| Table 119. Nagase ChemteX Corporation Major Business                                                                                                                                     |
| Table 120. Nagase ChemteX Corporation Electronic Underfill Encapsulants Product and Services                                                                                             |
| Table 121. Nagase ChemteX Corporation Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)   |
| Table 122. Nagase ChemteX Corporation Recent Developments/Updates                                                                                                                        |
| Table 123. Nagase ChemteX Corporation Competitive Strengths & Weaknesses                                                                                                                 |
| Table 124. Kyocera Corporation Basic Information, Manufacturing Base and Competitors                                                                                                     |
| Table 125. Kyocera Corporation Major Business                                                                                                                                            |
| Table 126. Kyocera Corporation Electronic Underfill Encapsulants Product and Services                                                                                                    |
| Table 127. Kyocera Corporation Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)          |
| Table 128. Kyocera Corporation Recent Developments/Updates                                                                                                                               |

Table 129. Kyocera Corporation Competitive Strengths & Weaknesses

Table 130. ThreeBond Co., Ltd. Basic Information, Manufacturing Base and Competitors

Table 131. ThreeBond Co., Ltd. Major Business

Table 132. ThreeBond Co., Ltd. Electronic Underfill Encapsulants Product and Services

Table 133. ThreeBond Co., Ltd. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 134. ThreeBond Co., Ltd. Recent Developments/Updates

Table 135. ThreeBond Co., Ltd. Competitive Strengths & Weaknesses

Table 136. H.B. Fuller Company Basic Information, Manufacturing Base and Competitors

Table 137. H.B. Fuller Company Major Business

Table 138. H.B. Fuller Company Electronic Underfill Encapsulants Product and Services

Table 139. H.B. Fuller Company Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 140. H.B. Fuller Company Recent Developments/Updates

Table 141. H.B. Fuller Company Competitive Strengths & Weaknesses

Table 142. Parker Hannifin Corporation Basic Information, Manufacturing Base and Competitors

Table 143. Parker Hannifin Corporation Major Business

Table 144. Parker Hannifin Corporation Electronic Underfill Encapsulants Product and Services

Table 145. Parker Hannifin Corporation Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 146. Parker Hannifin Corporation Recent Developments/Updates

Table 147. Parker Hannifin Corporation Competitive Strengths & Weaknesses

Table 148. AI Technology, Inc. Basic Information, Manufacturing Base and Competitors

Table 149. AI Technology, Inc. Major Business

Table 150. AI Technology, Inc. Electronic Underfill Encapsulants Product and Services

Table 151. AI Technology, Inc. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 152. AI Technology, Inc. Recent Developments/Updates

Table 153. AI Technology, Inc. Competitive Strengths & Weaknesses

Table 154. Zymet Inc. Basic Information, Manufacturing Base and Competitors

Table 155. Zymet Inc. Major Business

Table 156. Zymet Inc. Electronic Underfill Encapsulants Product and Services

Table 157. Zymet Inc. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 158. Zymet Inc. Recent Developments/Updates

Table 159. Zymet Inc. Competitive Strengths & Weaknesses

Table 160. Master Bond Inc. Basic Information, Manufacturing Base and Competitors

Table 161. Master Bond Inc. Major Business

Table 162. Master Bond Inc. Electronic Underfill Encapsulants Product and Services

Table 163. Master Bond Inc. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 164. Master Bond Inc. Recent Developments/Updates

Table 165. Master Bond Inc. Competitive Strengths & Weaknesses

Table 166. Element Solutions Inc Basic Information, Manufacturing Base and Competitors

Table 167. Element Solutions Inc Major Business

Table 168. Element Solutions Inc Electronic Underfill Encapsulants Product and Services

Table 169. Element Solutions Inc Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 170. Element Solutions Inc Recent Developments/Updates

Table 171. Element Solutions Inc Competitive Strengths & Weaknesses

Table 172. AIM Solder Basic Information, Manufacturing Base and Competitors

Table 173. AIM Solder Major Business

Table 174. AIM Solder Electronic Underfill Encapsulants Product and Services

Table 175. AIM Solder Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 176. AIM Solder Recent Developments/Updates

Table 177. AIM Solder Competitive Strengths & Weaknesses

Table 178. DELO Industrial Adhesives Basic Information, Manufacturing Base and Competitors

Table 179. DELO Industrial Adhesives Major Business

Table 180. DELO Industrial Adhesives Electronic Underfill Encapsulants Product and Services

Table 181. DELO Industrial Adhesives Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market

Share (2021-2026)

Table 182. DELO Industrial Adhesives Recent Developments/Updates

Table 183. DELO Industrial Adhesives Competitive Strengths & Weaknesses

Table 184. Dr. H?nle AG Basic Information, Manufacturing Base and Competitors

Table 185. Dr. H?nle AG Major Business

Table 186. Dr. H?nle AG Electronic Underfill Encapsulants Product and Services

Table 187. Dr. H?nle AG Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 188. Dr. H?nle AG Recent Developments/Updates

Table 189. Dr. H?nle AG Competitive Strengths & Weaknesses

Table 190. Protavic International Basic Information, Manufacturing Base and Competitors

Table 191. Protavic International Major Business

Table 192. Protavic International Electronic Underfill Encapsulants Product and Services

Table 193. Protavic International Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 194. Protavic International Recent Developments/Updates

Table 195. Protavic International Competitive Strengths & Weaknesses

Table 196. ROARTIS bvba Basic Information, Manufacturing Base and Competitors

Table 197. ROARTIS bvba Major Business

Table 198. ROARTIS bvba Electronic Underfill Encapsulants Product and Services

Table 199. ROARTIS bvba Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 200. ROARTIS bvba Recent Developments/Updates

Table 201. ROARTIS bvba Competitive Strengths & Weaknesses

Table 202. Darbond Technology Co., Ltd. Basic Information, Manufacturing Base and Competitors

Table 203. Darbond Technology Co., Ltd. Major Business

Table 204. Darbond Technology Co., Ltd. Electronic Underfill Encapsulants Product and Services

Table 205. Darbond Technology Co., Ltd. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 206. Darbond Technology Co., Ltd. Recent Developments/Updates

Table 207. Darbond Technology Co., Ltd. Competitive Strengths & Weaknesses

Table 208. Weldtone Technology Co., Ltd. Basic Information, Manufacturing Base and Competitors

Table 209. Weldtone Technology Co., Ltd. Major Business

Table 210. Weldtone Technology Co., Ltd. Electronic Underfill Encapsulants Product and Services

Table 211. Weldtone Technology Co., Ltd. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 212. Weldtone Technology Co., Ltd. Recent Developments/Updates

Table 213. Weldtone Technology Co., Ltd. Competitive Strengths & Weaknesses

Table 214. Hubei Huitian New Materials Co., Ltd. Basic Information, Manufacturing Base and Competitors

Table 215. Hubei Huitian New Materials Co., Ltd. Major Business

Table 216. Hubei Huitian New Materials Co., Ltd. Electronic Underfill Encapsulants Product and Services

Table 217. Hubei Huitian New Materials Co., Ltd. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 218. Hubei Huitian New Materials Co., Ltd. Recent Developments/Updates

Table 219. Hubei Huitian New Materials Co., Ltd. Competitive Strengths & Weaknesses

Table 220. WaferChem Technology Corp. Basic Information, Manufacturing Base and Competitors

Table 221. WaferChem Technology Corp. Major Business

Table 222. WaferChem Technology Corp. Electronic Underfill Encapsulants Product and Services

Table 223. WaferChem Technology Corp. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 224. WaferChem Technology Corp. Recent Developments/Updates

Table 225. WaferChem Technology Corp. Competitive Strengths & Weaknesses

Table 226. Everwide Chemical Co. Basic Information, Manufacturing Base and Competitors

Table 227. Everwide Chemical Co. Major Business

Table 228. Everwide Chemical Co. Electronic Underfill Encapsulants Product and Services

Table 229. Everwide Chemical Co. Electronic Underfill Encapsulants Production (Tons), Price (US\$/Ton), Production Value (USD Million), Gross Margin and Market Share (2021-2026)

Table 230. Everwide Chemical Co. Recent Developments/Updates

Table 231. Everwide Chemical Co. Competitive Strengths & Weaknesses

Table 232. Global Key Players of Electronic Underfill Encapsulants Upstream (Raw Materials)

Table 233. Global Electronic Underfill Encapsulants Typical Customers

Table 234. Electronic Underfill Encapsulants Typical Distributors

## List Of Figures

### LIST OF FIGURES

Figure 1. Electronic Underfill Encapsulants Picture

Figure 2. World Electronic Underfill Encapsulants Production Value: 2021 & 2025 & 2032, (USD Million)

Figure 3. World Electronic Underfill Encapsulants Production Value and Forecast (2021-2032) & (USD Million)

Figure 4. World Electronic Underfill Encapsulants Production (2021-2032) & (Tons)

Figure 5. World Electronic Underfill Encapsulants Average Price (2021-2032) & (US\$/Ton)

Figure 6. World Electronic Underfill Encapsulants Production Value Market Share by Region (2021-2032)

Figure 7. World Electronic Underfill Encapsulants Production Market Share by Region (2021-2032)

Figure 8. North America Electronic Underfill Encapsulants Production (2021-2032) & (Tons)

Figure 9. Europe Electronic Underfill Encapsulants Production (2021-2032) & (Tons)

Figure 10. China Electronic Underfill Encapsulants Production (2021-2032) & (Tons)

Figure 11. Japan Electronic Underfill Encapsulants Production (2021-2032) & (Tons)

Figure 12. Electronic Underfill Encapsulants Market Drivers

Figure 13. Factors Affecting Demand

Figure 14. World Electronic Underfill Encapsulants Consumption (2021-2032) & (Tons)

Figure 15. World Electronic Underfill Encapsulants Consumption Market Share by Region (2021-2032)

Figure 16. United States Electronic Underfill Encapsulants Consumption (2021-2032) & (Tons)

Figure 17. China Electronic Underfill Encapsulants Consumption (2021-2032) & (Tons)

Figure 18. Europe Electronic Underfill Encapsulants Consumption (2021-2032) & (Tons)

Figure 19. Japan Electronic Underfill Encapsulants Consumption (2021-2032) & (Tons)

Figure 20. South Korea Electronic Underfill Encapsulants Consumption (2021-2032) & (Tons)

Figure 21. ASEAN Electronic Underfill Encapsulants Consumption (2021-2032) & (Tons)

Figure 22. India Electronic Underfill Encapsulants Consumption (2021-2032) & (Tons)

Figure 23. Producer Shipments of Electronic Underfill Encapsulants by Manufacturer Revenue (\$MM) and Market Share (%): 2025

Figure 24. Global Four-firm Concentration Ratios (CR4) for Electronic Underfill

Encapsulants Markets in 2025

Figure 25. Global Four-firm Concentration Ratios (CR8) for Electronic Underfill

Encapsulants Markets in 2025

Figure 26. United States VS China: Electronic Underfill Encapsulants Production Value Market Share Comparison (2021 & 2025 & 2032)

Figure 27. United States VS China: Electronic Underfill Encapsulants Production Market Share Comparison (2021 & 2025 & 2032)

Figure 28. United States VS China: Electronic Underfill Encapsulants Consumption Market Share Comparison (2021 & 2025 & 2032)

Figure 29. United States Based Manufacturers Electronic Underfill Encapsulants Production Market Share 2025

Figure 30. China Based Manufacturers Electronic Underfill Encapsulants Production Market Share 2025

Figure 31. Rest of World Based Manufacturers Electronic Underfill Encapsulants Production Market Share 2025

Figure 32. World Electronic Underfill Encapsulants Production Value by Type, (USD Million), 2021 & 2025 & 2032

Figure 33. World Electronic Underfill Encapsulants Production Value Market Share by Type in 2025

Figure 34. Capillary Flow Underfill

Figure 35. Molded Underfill

Figure 36. No Flow Underfill

Figure 37. Others

Figure 38. World Electronic Underfill Encapsulants Production Market Share by Type (2021-2032)

Figure 39. World Electronic Underfill Encapsulants Production Value Market Share by Type (2021-2032)

Figure 40. World Electronic Underfill Encapsulants Average Price by Type (2021-2032) & (US\$/Ton)

Figure 41. World Electronic Underfill Encapsulants Production Value by Resin Chemistry, (USD Million), 2021 & 2025 & 2032

Figure 42. World Electronic Underfill Encapsulants Production Value Market Share by Resin Chemistry in 2025

Figure 43. Epoxy Based Materials

Figure 44. Modified Epoxy and Hybrid Materials

Figure 45. Others

Figure 46. World Electronic Underfill Encapsulants Production Market Share by Resin Chemistry (2021-2032)

Figure 47. World Electronic Underfill Encapsulants Production Value Market Share by

Resin Chemistry (2021-2032)

Figure 48. World Electronic Underfill Encapsulants Average Price by Resin Chemistry (2021-2032) & (US\$/Ton)

Figure 49. World Electronic Underfill Encapsulants Production Value by Package Type, (USD Million), 2021 & 2025 & 2032

Figure 50. World Electronic Underfill Encapsulants Production Value Market Share by Package Type in 2025

Figure 51. Flip Chip Packages

Figure 52. BGA and CSP Packages

Figure 53. WLP and Fan Out Packages

Figure 54. Others

Figure 55. World Electronic Underfill Encapsulants Production Market Share by Package Type (2021-2032)

Figure 56. World Electronic Underfill Encapsulants Production Value Market Share by Package Type (2021-2032)

Figure 57. World Electronic Underfill Encapsulants Average Price by Package Type (2021-2032) & (US\$/Ton)

Figure 58. World Electronic Underfill Encapsulants Production Value by End Use Industry, (USD Million), 2021 & 2025 & 2032

Figure 59. World Electronic Underfill Encapsulants Production Value Market Share by End Use Industry in 2025

Figure 60. Consumer Electronics

Figure 61. Computing and Communications Infrastructure

Figure 62. Automotive Electronics

Figure 63. Others

Figure 64. World Electronic Underfill Encapsulants Production Market Share by End Use Industry (2021-2032)

Figure 65. World Electronic Underfill Encapsulants Production Value Market Share by End Use Industry (2021-2032)

Figure 66. World Electronic Underfill Encapsulants Average Price by End Use Industry (2021-2032) & (US\$/Ton)

Figure 67. World Electronic Underfill Encapsulants Production Value by Application, (USD Million), 2021 & 2025 & 2032

Figure 68. World Electronic Underfill Encapsulants Production Value Market Share by Application in 2025

Figure 69. Package Level Underfill

Figure 70. Board Level Underfill

Figure 71. Others

Figure 72. World Electronic Underfill Encapsulants Production Market Share by

Application (2021-2032)

Figure 73. World Electronic Underfill Encapsulants Production Value Market Share by Application (2021-2032)

Figure 74. World Electronic Underfill Encapsulants Average Price by Application (2021-2032) & (US\$/Ton)

Figure 75. Electronic Underfill Encapsulants Industry Chain

Figure 76. Electronic Underfill Encapsulants Procurement Model

Figure 77. Electronic Underfill Encapsulants Sales Model

Figure 78. Electronic Underfill Encapsulants Sales Channels, Direct Sales, and Distribution

Figure 79. Methodology

Figure 80. Research Process and Data Source

## I would like to order

Product name: Global Electronic Underfill Encapsulants Supply, Demand and Key Producers, 2026-2032

Product link: <https://marketpublishers.com/r/G893B92C881FEN.html>

Price: US\$ 4,480.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

[info@marketpublishers.com](mailto:info@marketpublishers.com)

## Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/G893B92C881FEN.html>